



P-Channel 60-V (D-S) 175 °C MOSFET

PRODUCT SUMMARY

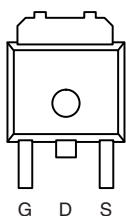
V_{DS} (V)	$r_{DS(on)}$ (Ω)	I_D (A)	Q_g (Typ)
- 60	0.060 at $V_{GS} = - 10$ V	- 19	26
	0.077 at $V_{GS} = - 4.5$ V	- 16.8	

FEATURES

- TrenchFET® Power MOSFET
- 175 °C Junction Temperature

RoHS
COMPLIANT

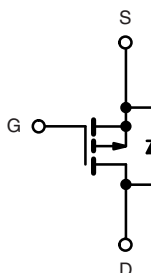
TO-252



Top View

Drain Connected to Tab

Ordering Information: SUD19P06-60L-E3 (Lead (Pb)-free)



P-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS $T_A = 25$ °C, unless otherwise noted

Parameter		Symbol	Limit	Unit
Drain-Source Voltage		V_{DS}	- 60	V
Gate-Source Voltage		V_{GS}	± 20	
Continuous Drain Current ($T_J = 175$ °C)	$T_C = 25$ °C	I_D	- 19	A
	$T_C = 125$ °C		- 11	
Pulsed Drain Current		I_{DM}	- 30	
Avalanche Current, Single Pulse		I_{AS}	- 22	
Repetitive Avalanche Energy, Single Pulse ^a		E_{AS}	24.2	mJ
Power Dissipation	$T_C = 25$ °C	P_D	46 ^c	W
	$T_A = 25$ °C		2.7 ^{b, c}	
Operating Junction and Storage Temperature Range		T_J, T_{stg}	- 55 to 175	°C

THERMAL RESISTANCE RATINGS

Parameter		Symbol	Typical	Maximum	Unit
Junction-to-Ambient ^b	$t \leq 10$ s	R_{thJA}	17	21	°C/W
	Steady State		45	55	
Junction-to-Case		R_{thJC}	2.7	3.25	

Notes:

a. Duty cycle ≤ 1 %.

b. When mounted on 1" square PCB (FR-4 material).

c. See SOA curve for voltage derating.



SPECIFICATIONS T _J = 25 °C, unless otherwise noted						
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Static						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0 V, I _D = - 250 μA	- 60			V
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = - 250 μA	- 1		- 3	V
Gate-Body Leakage	I _{GSS}	V _{DS} = 0 V, V _{GS} = ± 20 V			± 100	nA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = - 60 V, V _{GS} = 0 V			- 1	μA
		V _{DS} = - 60 V, V _{GS} = 0 V, T _J = 125 °C			- 50	
		V _{DS} = - 60 V, V _{GS} = 0 V, T _J = 175 °C			- 150	
On-State Drain Current ^a	I _{D(on)}	V _{DS} = - 5 V, V _{GS} = - 10 V	- 30			A
Drain-Source On-State Resistance ^a	r _{DS(on)}	V _{GS} = - 10 V, I _D = - 10 A		0.048	0.060	Ω
		V _{GS} = - 10 V, I _D = - 16.8 A, T _J = 125 °C			0.102	
		V _{GS} = - 10 V, I _D = - 16.8 A, T _J = 175 °C			0.129	
		V _{GS} = - 4.5 V, I _D = - 5 A		0.061	0.077	
Forward Transconductance ^a	g _{fs}	V _{DS} = - 15 V, I _D = - 10 A		22		S
Dynamic ^b						
Input Capacitance	C _{iss}	V _{GS} = 0 V, V _{DS} = - 25 V, f = 1 MHz		1140	1710	pF
Output Capacitance	C _{oss}			130		
Reverse Transfer Capacitance	C _{rss}			90		
Total Gate Charge	Q _g	V _{DS} = - 30 V, V _{GS} = - 10 V, I _D = - 10 A		26	40	nC
Gate-Source Charge	Q _{gs}			4.5		
Gate-Drain Charge	Q _{gd}			7.0		
Gate Resistance	R _g	f = 1 MHz		7.0		Ω
Turn-On Delay Time ^c	t _{d(on)}	V _{DD} = - 30 V, R _L = 3 Ω I _D ≅ - 19 A, V _{GEN} = - 10 V, R _g = 2.5 Ω		8	15	ns
Rise Time ^c	t _r			9	15	
Turn-Off Delay Time ^c	t _{d(off)}			65	100	
Fall Time ^c	t _f			30	45	
Drain-Source Body Diode Characteristics (T _C = 25 °C) ^b						
Continuous Current	I _S				- 30	A
Pulsed Current	I _{SM}				- 30	
Forward Voltage ^a	V _{SD}	I _F = - 19 A, V _{GS} = 0 V		- 1.0	- 1.5	V
Reverse Recovery Time	t _{rr}	I _F = - 19 A, di/dt = 100 A/μs		41	61	ns

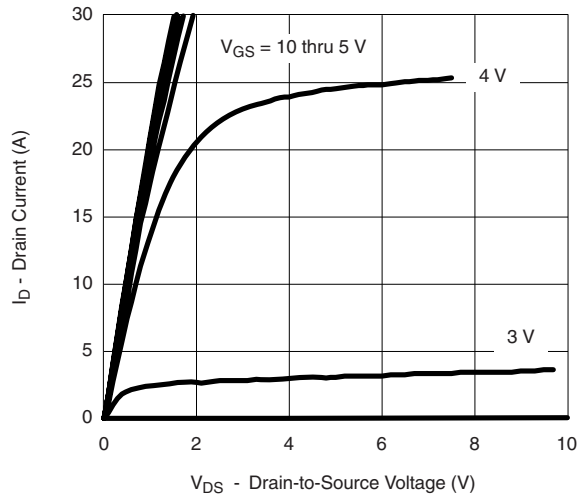
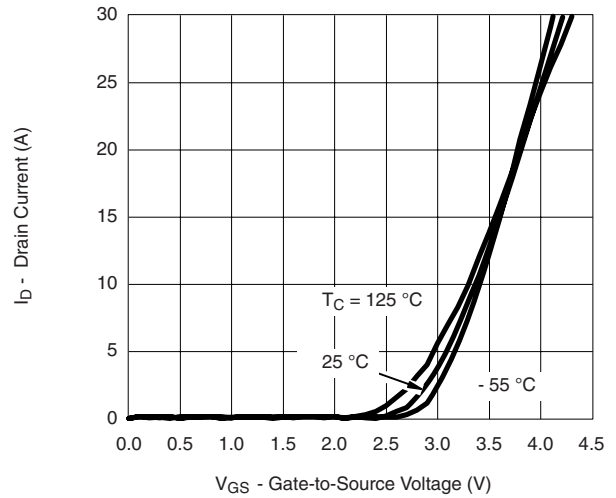
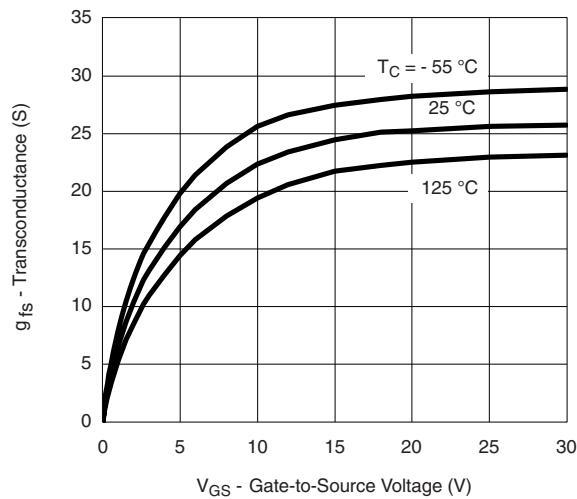
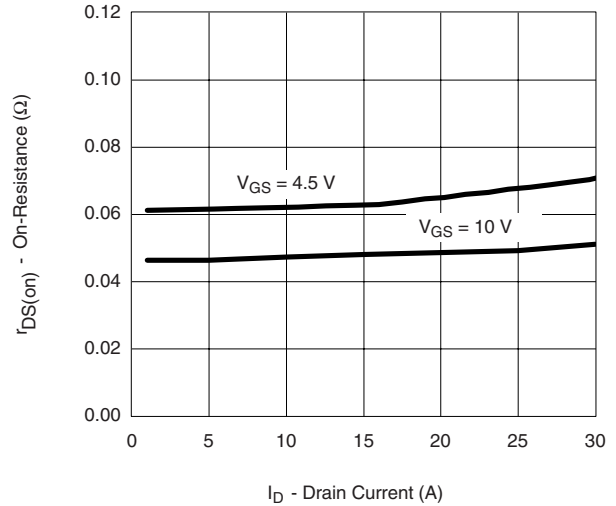
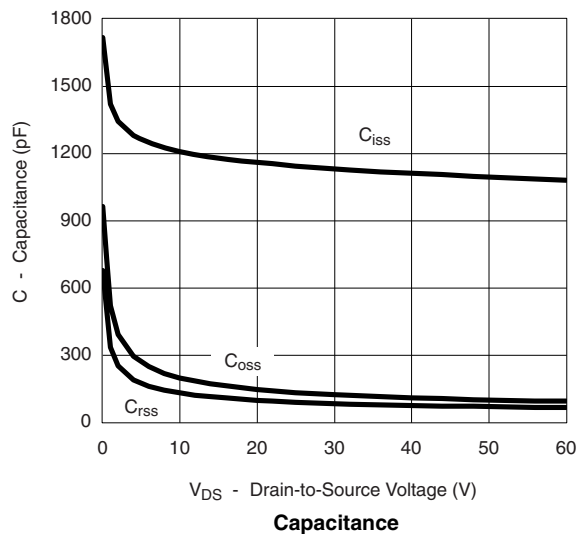
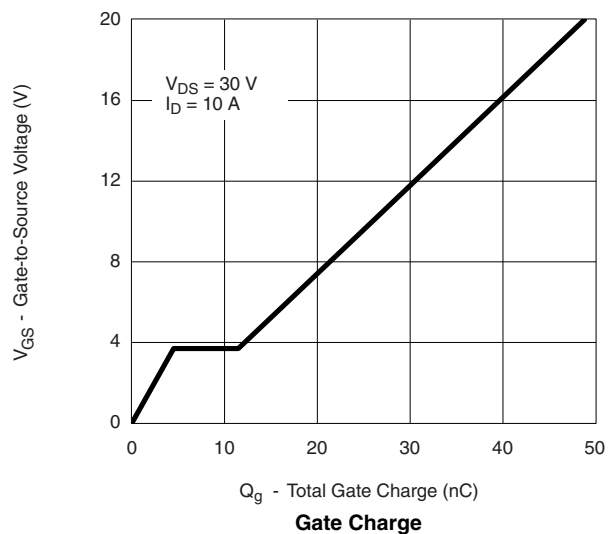
Notes:

a. Pulse test; pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$.

b. Guaranteed by design, not subject to production testing.

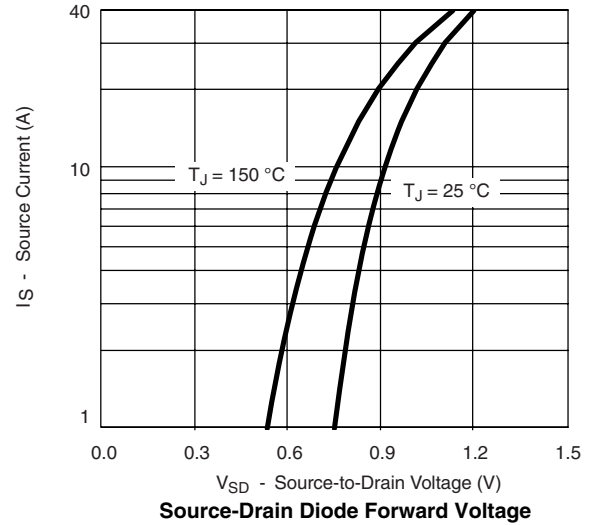
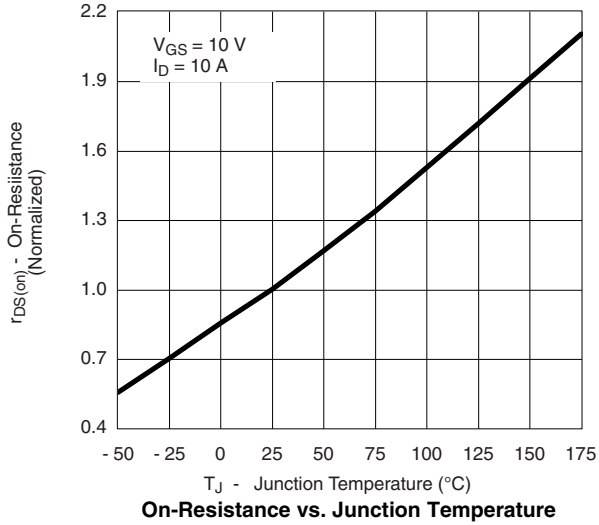
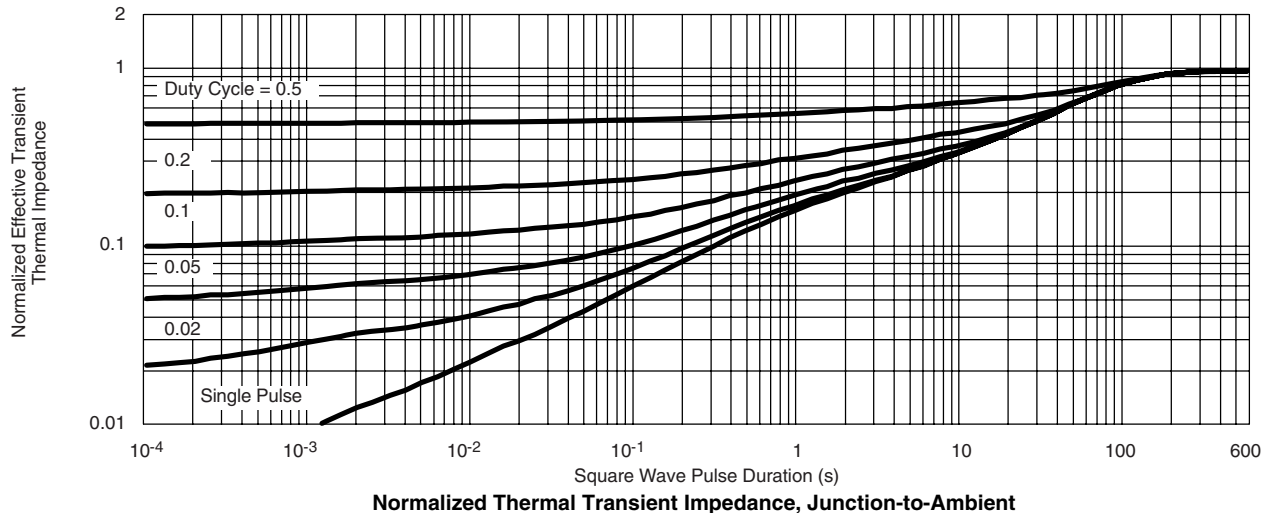
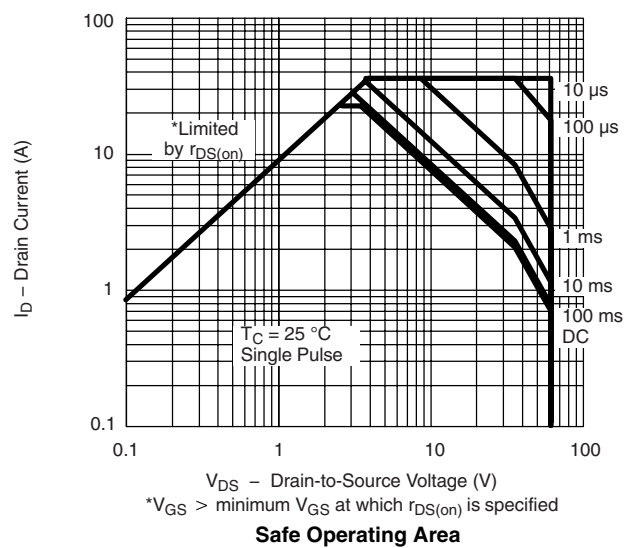
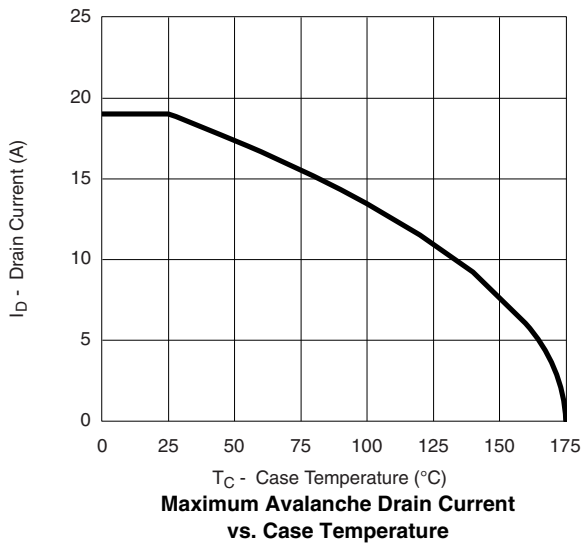
c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

**TYPICAL CHARACTERISTICS** 25 °C, unless otherwise noted**Output Characteristics****Transfer Characteristics****Transconductance****On-Resistance vs. Drain Current****Capacitance****Gate Charge**

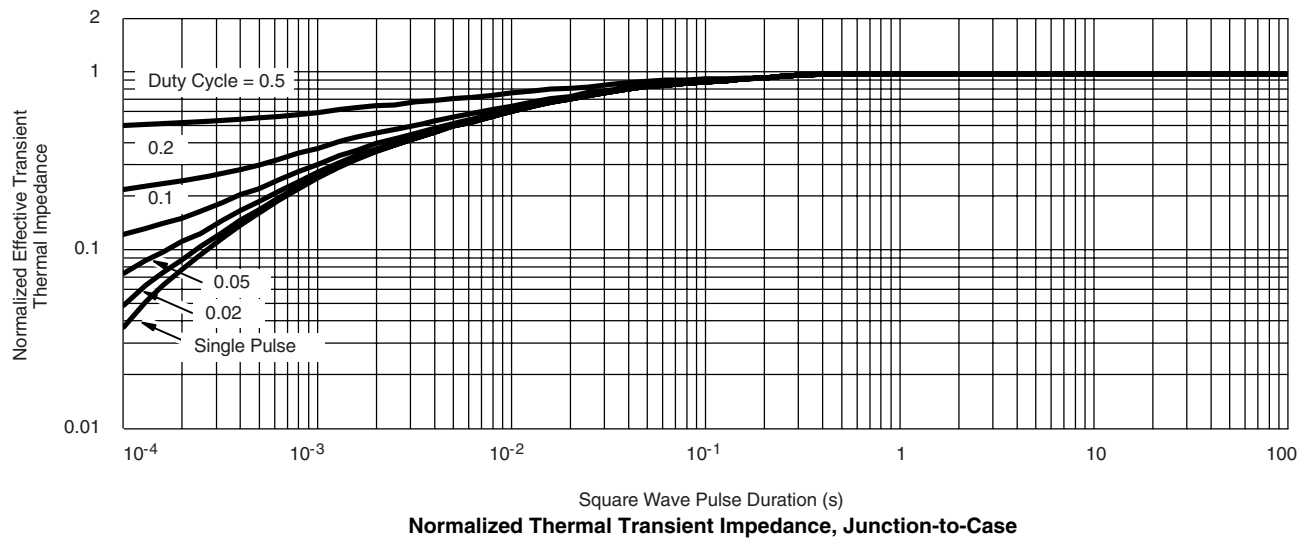
SUD19P06-60L

Vishay Siliconix

**TYPICAL CHARACTERISTICS** 25 °C, unless otherwise noted**THERMAL RATINGS**



THERMAL RATINGS



Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see <http://www.vishay.com/ppg?73103>



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